

# Memory Product Specification

DK.04GAK.F9QK2

4GB(2GB 256M x 64Bit x 2pcs) Kit

DDR3-1600MHz CL9 Overclocking Unbuffered DIMM

## Description:

The overclocking unbuffered Module is a kit of two 256M x 64bit of 2GB DDR3-1600MHz CL9-9-9-27 at 1.65v Memory Module.

The Module base on sixteen 128M x 8-bit DDR3 FBGA SDRAM components.

The SPDs are programmed to JEDEC standard latency DDR3-1333MHz of CL9-9-9-24 at 1.5v.

Memory Module intended for mounting into 240-pin edge connector sockets.

The electrical and mechanical specifications are as follows:

## Features:

- DDR3 Speed Grade : 1333Mbps
- Organization
  - 256M words × 64 bits, 2 ranks
- Mounting 16 pieces of 1G bits DDR3 SDRAM sealed in FBGA
- Package: 240-pin socket type dual in line memory module (DIMM)
  - PCB height: 1.181 inch ( 30.0mm )
  - Lead-free (RoHS compliant)
- Power supply: VDD = 1.5V ± 0.075V
- Eight internal banks for concurrent operation (components)
- Interface: SSTL\_15
- Burst lengths (BL): 8 and 4 with Burst Chop (BC)
- /CAS Latency (CL): 6, 7, 8, 9
- /CAS write latency (CWL): 5, 6, 7
- Precharge: auto precharge option for each burst access
- Refresh: auto-refresh, self-refresh
- Refresh cycles
  - Average refresh period
  - 7.8μs at 0°C ≤ TC ≤ +85°C
  - 3.9μs at +85°C < TC ≤ +95°C
- Operating case temperature range
  - TC = 0°C to +95°C

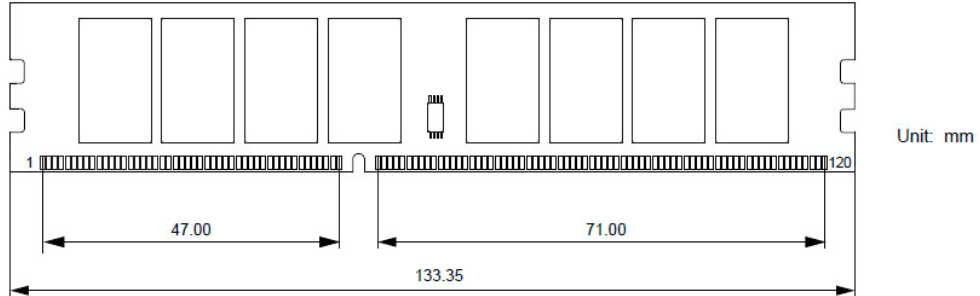
## Overclocking Datasheet w/ Intel XMP:

- Active Heatspreader
- DDR3 Speed Grade : 1600Mbps
- Power supply: VDD voltage : 1.65v  
VDDQ voltage : 1.65v
- CAS latency : CL9-9-9-27
- Bandwidth : 12800MB/s
- Serial presence detect with EEPROM.
- PCB height : 2.073 inch( 52.65mm ) w/ heatsink.
- RoHS Compliant
- Application : Gaming player

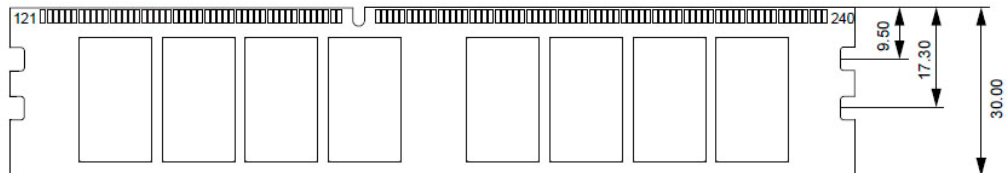


## Dimensions

Front side



Back side



## W/ Heatsink Assembly Dimensions



Retail Package

